IPC ASSOCIATION ELECTRONIC	© Copyright 20	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under international and Pan-American copyright conventions.			nder both Tl	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with low level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.									
752-21.1					Form Type * Distribute	Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Mater					ials and Mfg Information				
upplie	r Information														
Company name*				Company unique ID			Unique ID Authority					Response Date*			
onsemi												2023-06-12			
Contact N	ame		Title - Contact			P	Phone - Contact*				Email - Contact*				
Product-I	Env-Stewards		Product Enviro Compliance			N	NA				Product-Env-Stewards@onsemi.com				
uthorize	d Representative*		Title - Representative			P	Phone - Representative*				Email - Representative*				
Product-I	Env-Stewards		Product Envi	Product Enviro Compliance			NA				Product-Env-Stewards@onsemi.com				
	Requester Item Number Mfr It		m Number Mfr Item Name]	Effective Date	Version	n I	Manufacturing Site		W	eight*	UOM	Unit Type
		NCP59301DS50R4G 3A 5.0V		3A 5.0V VLDO R	.0V VLDO REGULATOR		2023-06-12				16	517.91	mg	Each	
Ianufa	cturing Process Info	rmation												·	
	Terminal Plating / Grid Array Material		Terminal Base Alloy J-STD-02		-STD-020 MSL R	Rating	Peak Process Body Temperatu		ire Max Time at Peak Temperatu		e Numb	per of Reflow Cyc	les		
Matte Tin (Sn) - annealed		CU Alloy 1		L		260 C		C	30 seco		second	3			
omments	i														
vel 1 - m	aximum time at peak temp	erature during so	ldering is 10-3	30 seconds											
or more	information regarding mat	erial composition	please refer to	page 3											

RoHS Material Composition Declaration			Declaration Type *	Detailed							
RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).											
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledges and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its paragraph. If the Company and the Supplier shall apply that agreement, will be the sole and exclusivesource of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the warranty rights and/or remedies of Supplier's Standard Terms and Conditions of Sale applicable to such part shall apply.											
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted substance	s per the definition above except for selected exemp	tions Supplier Acceptance	* Accepted							
Exemption: 7a: Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead).											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
Instructions: Complete all of the required f Requester) and click on Submit Form to ha		Accepted" on the Supplier Acceptance drop-dow	n. This will display the signature area. Digita	lly sign the declaration (if required by the							
Supplier Digital Signature Ra	astislav Drska	-En									

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	0.19	mg	Supplier	Silicon (Si)	7440-21-3		0.19	mg
Die Attach	11.31	mg	A	Lead (Pb)	7439-92-1	7a	10.7445	mg
			Supplier	Tin (Sn)	7440-31-5		0.5655	mg
Lead Frame	851.27	mg	В	Nickel (Ni)	7440-02-0		2.5538	mg
			Supplier	Copper (Cu)	7440-50-8		848.7162	mg
Mold Compound-Black	727.25			Epoxy resin	proprietary data		36.3625	mg
			Supplier	Phenolic Resin	Proprietary Data		36.3625	mg
			Supplier	Ortho Cresol Novolac Resin	29690-82-2		14.545	mg
			Supplier	Carbon Black (C)	1333-86-4		3.6363	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		636.3438	mg
Plating	27.15	mg	Supplier	Tin (Sn)	7440-31-5		27.15	mg
Wire Bond - Cu	0.74	mg	Supplier	Copper (Cu)	7440-50-8		0.74	mg